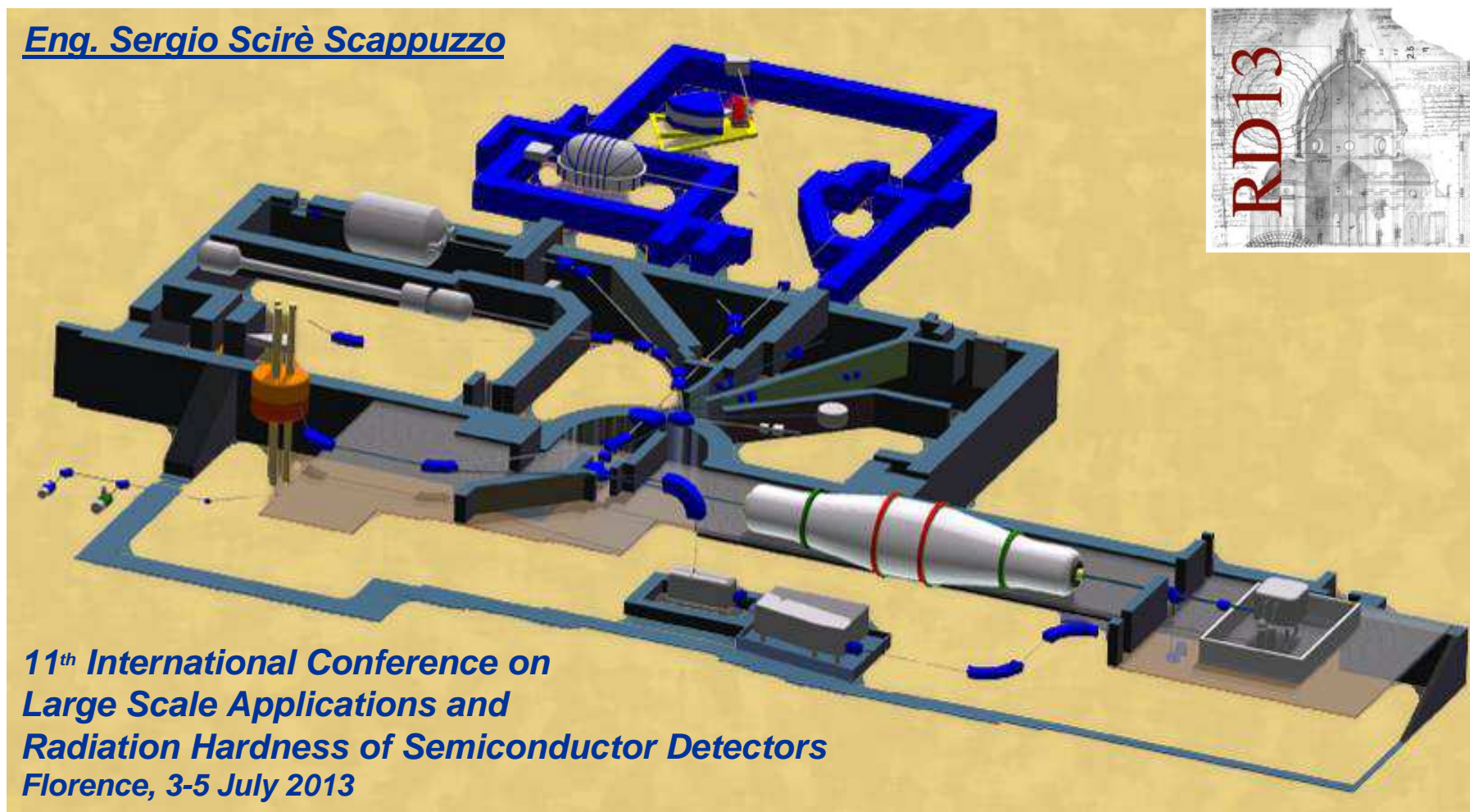


Single Event Effects Irradiation Tests at INFN-LNS

Eng. Sergio Scirè Scappuzzo

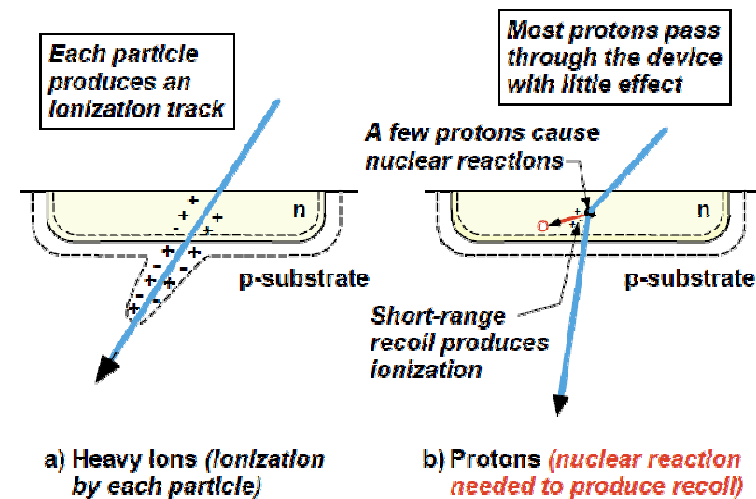
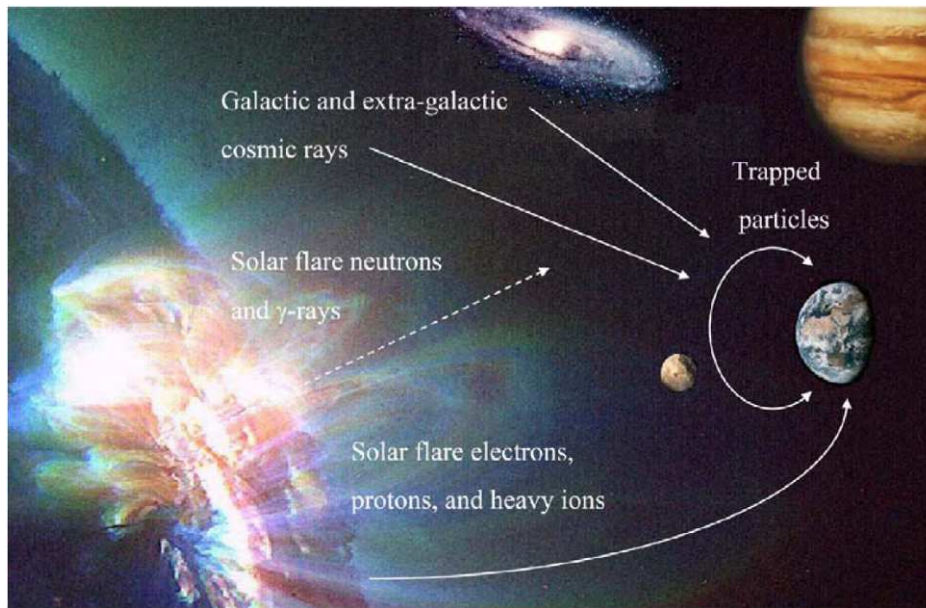


**11th International Conference on
Large Scale Applications and
Radiation Hardness of Semiconductor Detectors
Florence, 3-5 July 2013**

Introduction

Photons, electrons, protons and heavy ions produce ionization when they travel through matter

*The use of microelectronic devices in spacecraft requires that these devices **preserve their functionality** in the radiation environment found in space*



Need to reproduce in laboratory radiation damage into electronic devices



Radiation effects

Total Ionizing Dose (TID)
Usually dominated by protons



*Trapped charge can affect
device performance,
e.g., create a threshold
voltage shift in MOSFET devices*

Displacement Damage (DD)



*Occur in semiconductor
materials **due to scattering**
interactions of incident particles,
with the atoms of the
semiconductor lattice*

Single Event Effects (SEE)

- *Hard / Permanent*
- *Soft / Recoverable*
- *SEU, SET, SEL, SEGR, SEB ...*



*Occur when a single energetic
particle is capable of creating
an **observable effect** in a device*



Guidelines for SEE tests

Required facility equipment:

- Radiation Source
- Dosimetry
- Accurate positioning system
- Vacuum chamber
- Test Board and Cabling
- Availability of suitable

Linear Energy Transfer (LET)



Guidelines for SEE tests used:

- ESCC Basic Specification No. 25100
- Military standard MIL-STD-750E



Source: heavy ions

Range in Silicon: $> 30 \mu\text{m}$

Variable flux: 10^2 - 10^5 ions/cm²/s

Preferably in-vacuum

Accurate alignment and rotation of device to the beam

Flux

continuous monitoring with $\pm 10\%$ accuracy

Source: protons

Energy: 20-200 MeV

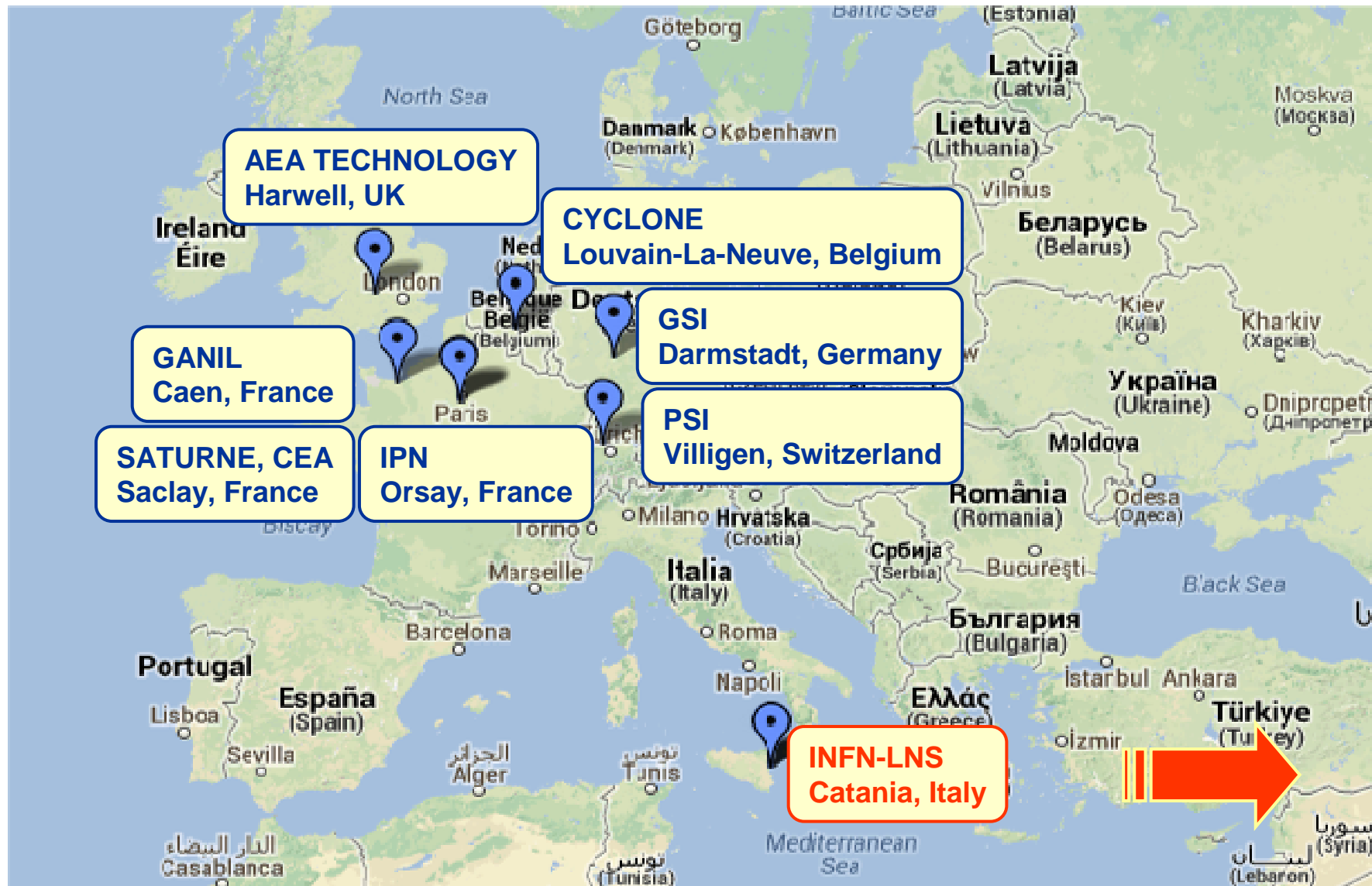
Variable flux: 10^5 - 10^8 p/cm²/s

Preferably In-air

Exposure of device normal to the beam

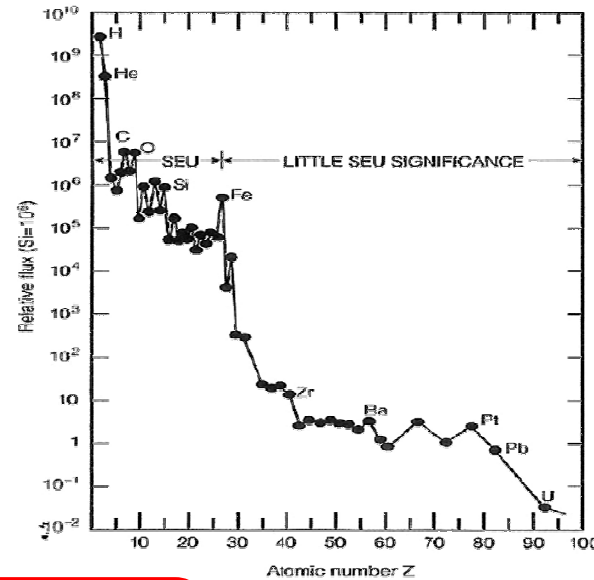


Some European Facilities commonly used for SEE testing



The Superconductive Cyclotron at LNS

compact 3-sector machine
magnetic field 2.2 - 4.8 T
superconducting Nb-Ti coils @ 4.2 °K



p , ^{12}C beams for radiobiology
 p , ^{20}Ne , ^{40}Ar , ^{84}Kr , ^{129}Xe , ^{197}Au beams
for radiation hardness tests

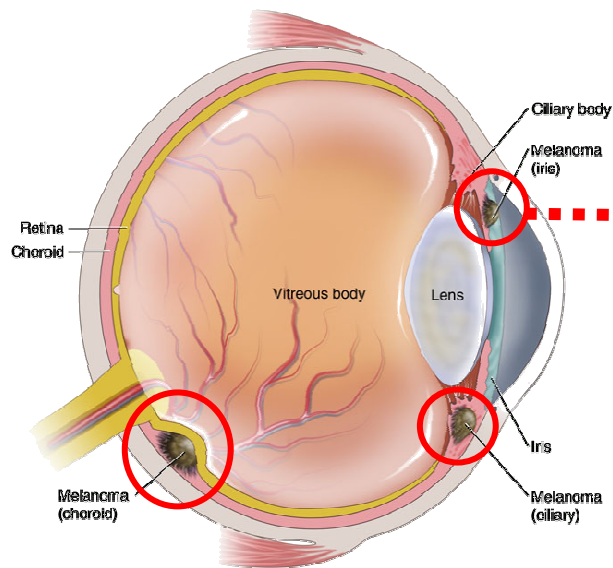
Change of ion beam takes approximately 5 hours.
The “ions cocktail” allows to change the
accelerated species with few minutes tuning

^AX	E (MeV/a.m.u.)
H_2^+	62,80
H_3^+	30,35,45
$^2\text{D}^+$	35,62,80
^4He	25,80
He-H	10, 21
^9Be	45
^{12}C	23,62,80
^{13}C	45,55
^{14}N	62,80
^{16}O	21,25,55,62,80
^{18}O	15,55
^{19}F	35,40,50
^{20}Ne	20,40,45,62
^{24}Mg	50
^{36}Ar	16,38,42
^{40}Ar	15,20,40
^{40}Ca	10,25,40,45
^{48}Ca	10,45
^{58}Ni	16,23,25,30,35,40
^{45}Ni	25,35
$^{68,70}\text{Zn}$	40
^{74}Ge	40
^{78}Kr	10
^{84}Kr	20
^{86}Kr	10,15,20,25
^{93}Nb	15,17,23,30,38
^{112}Sn	15.5,35,43.5
^{116}Sn	23,30,38
^{124}Sn	15,25,30,35
^{129}Xe	20,21,23,35
^{197}Au	10,15,20,21,23
^{208}Pb	10



The CATANA proton irradiation room

- In-air only
- Mainly dedicated to proton therapy
- Dosimetry and radiobiology experiments
- **Tests for radiation hardness of electronic components**
- Quick and easy positioning systems (resolution < 1 mm)
- Proton dose rates range: 1 to 100 Gy/min

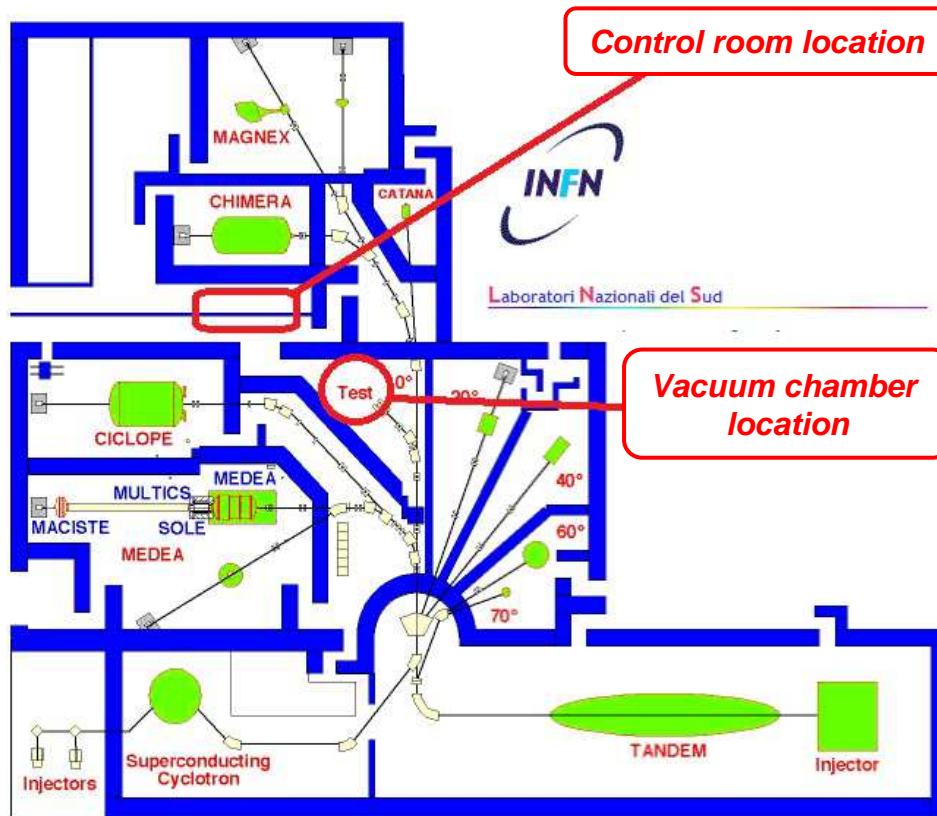


Treatment of eye melanoma



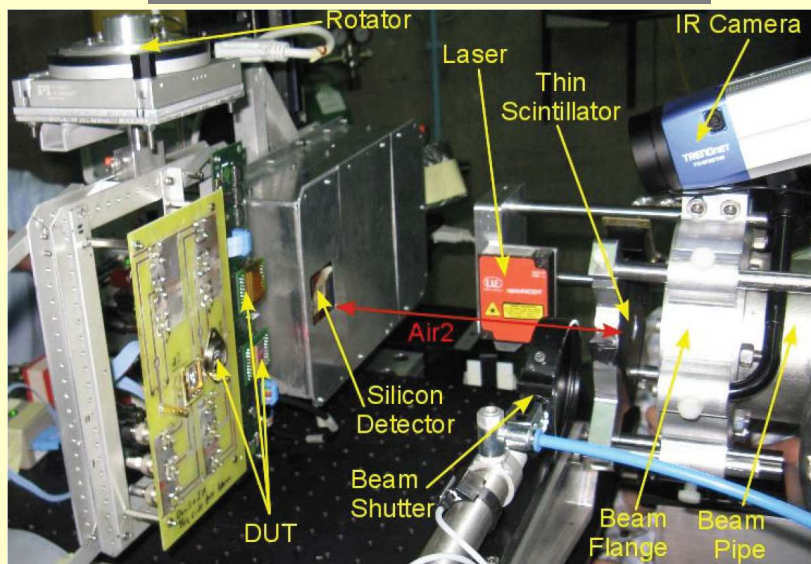
The “0 degree” irradiation chamber

*Multi flanged vacuum chamber
300 liters volume (diameter 60 cm, length 100 cm)
High level vacuum (below 10^{-5} mbar in two hours)
Distance to Control Room about 20 m*



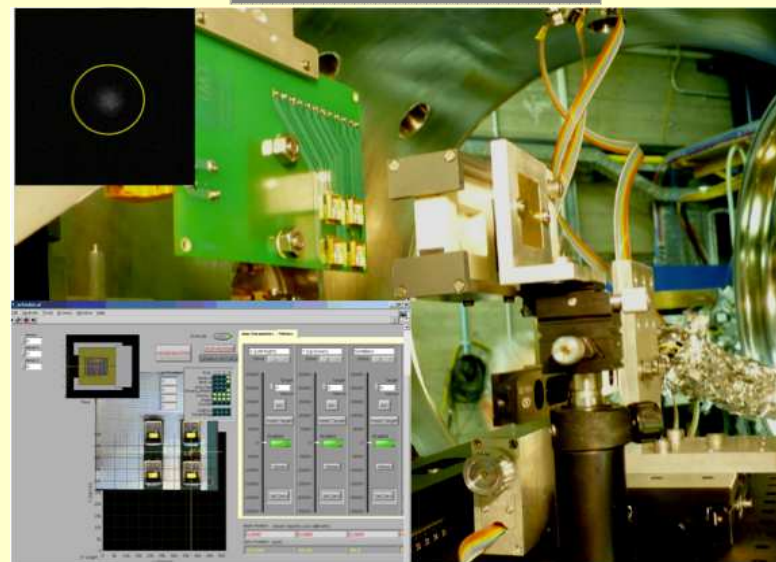
Irradiation expertises at INFN-LNS with italian companies

since 2007



In-air irradiation

since 2011



In-vacuum irradiation

Forthcoming collaborations with ASI and ESA ?

In vacuum irradiation setup

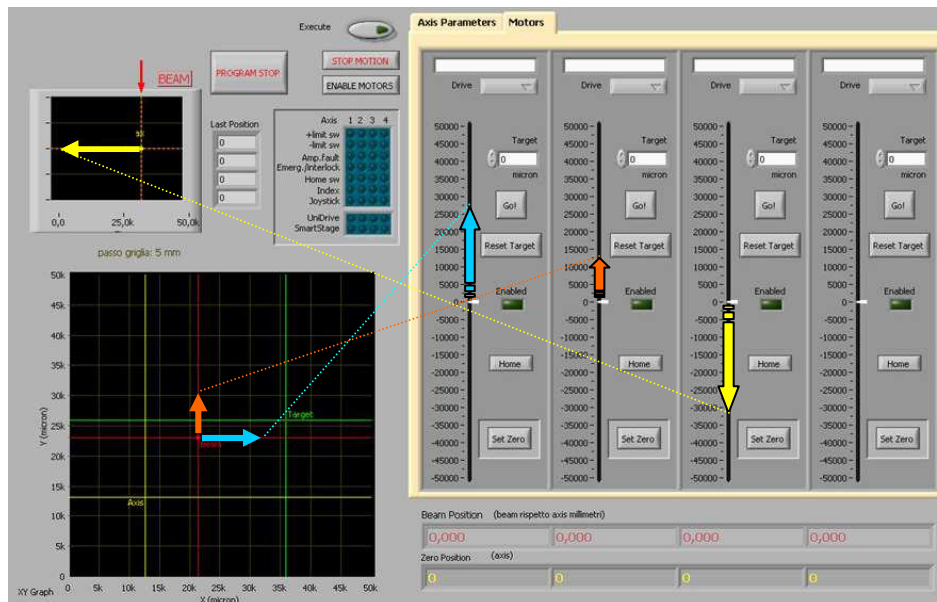
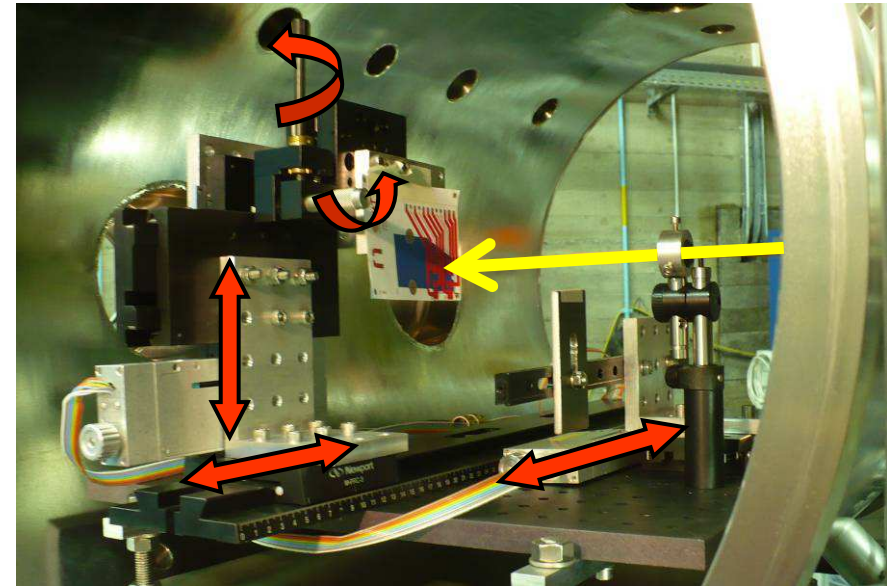
X-Y configuration linear stage actuators

→ 50 nm encoder resolution

→ Available exposure area 40x40 mm²

θ_y θ_z manual rotation

Removable dosimetric apparatus

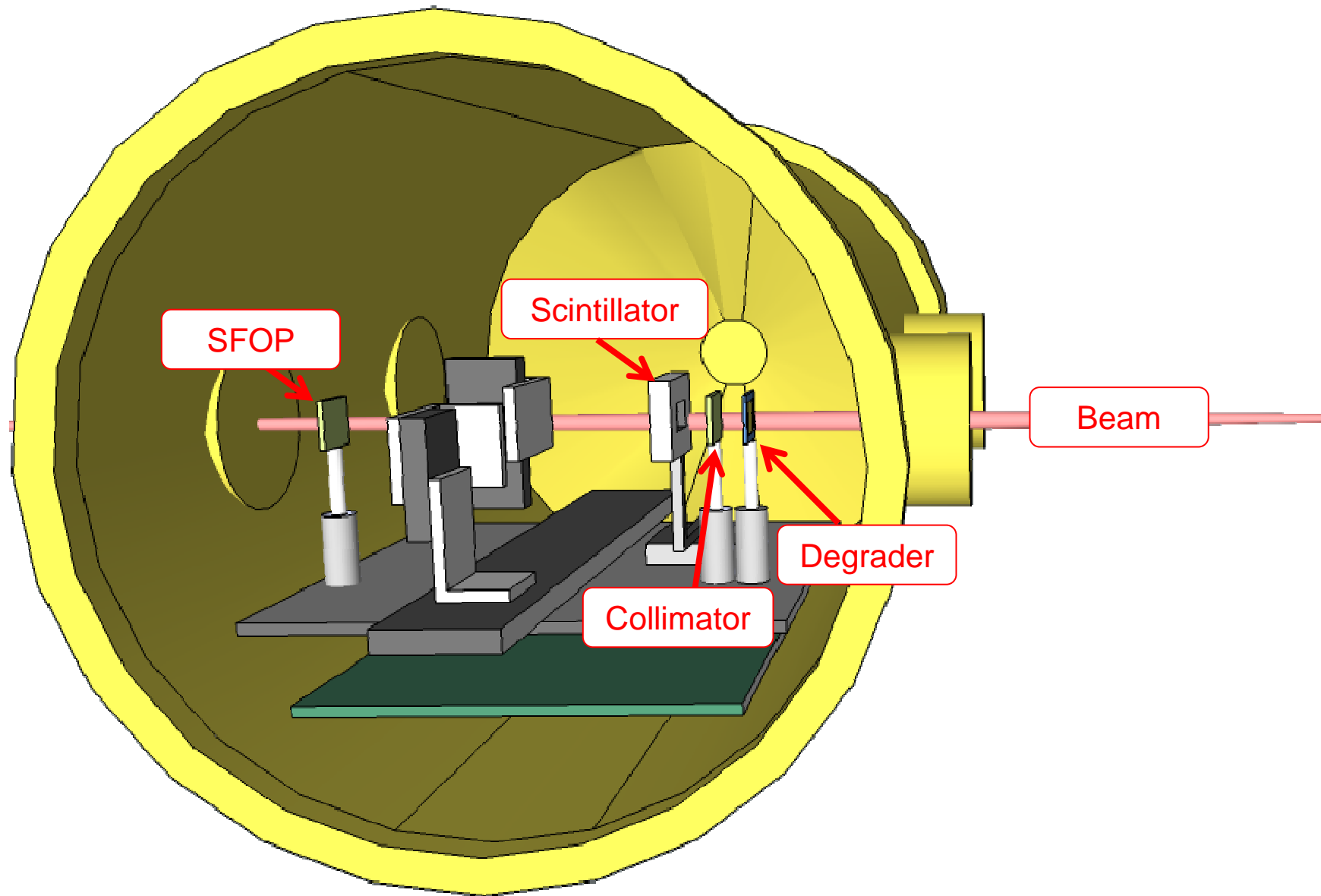


- Exposure area view
- Absolute and relative coordinates
- Beam spot in respect to devices
- Irradiation point targeting

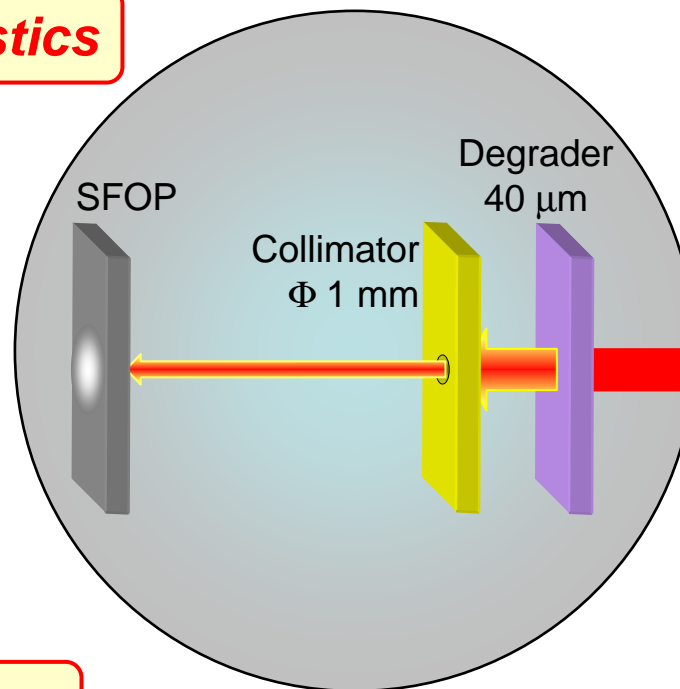
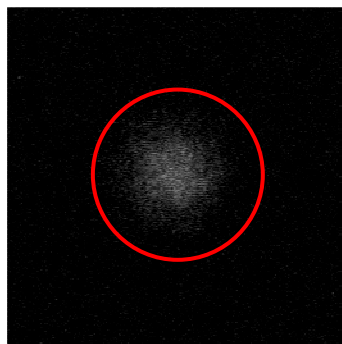
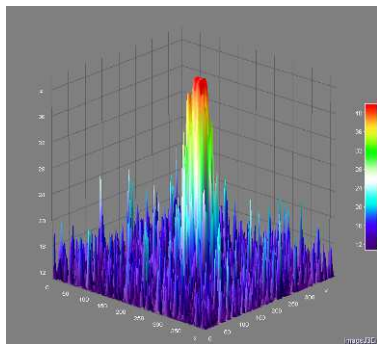
PCB alignment and removal from beam line



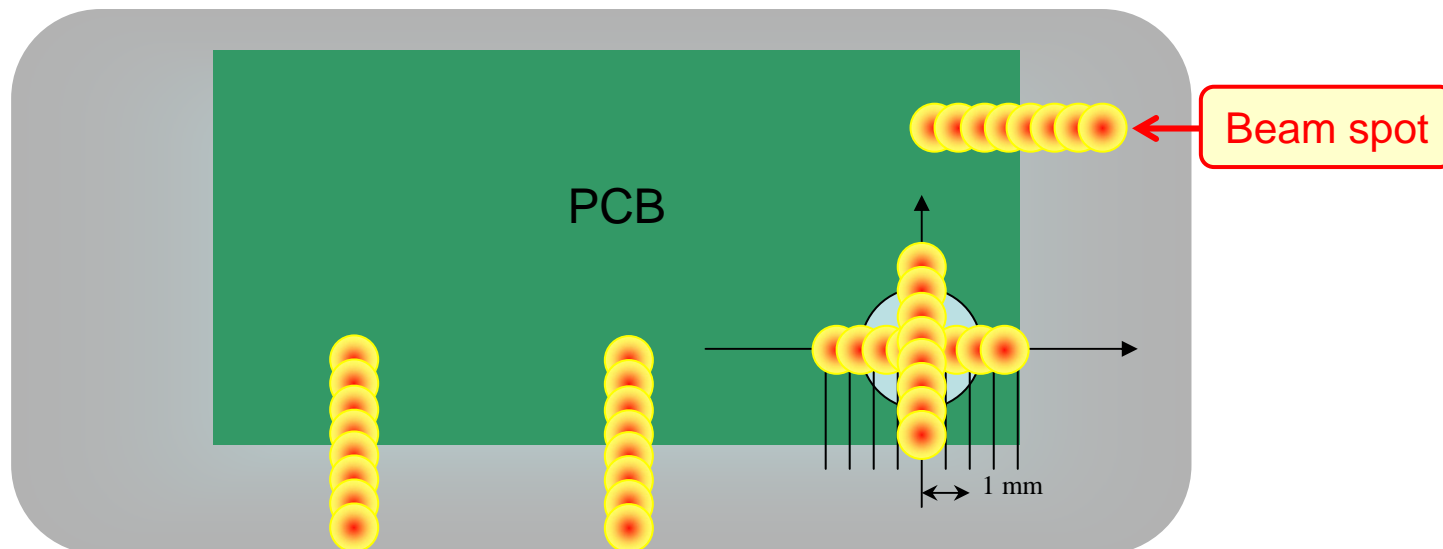
Schematic view of the experimental setup



Beam diagnostics

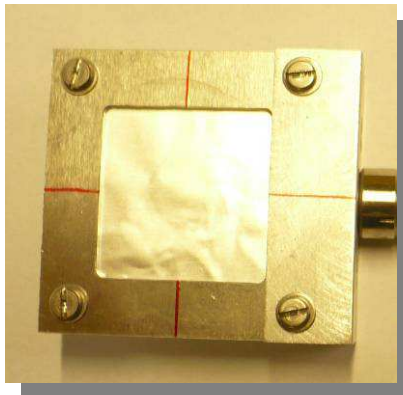


PCB alignment

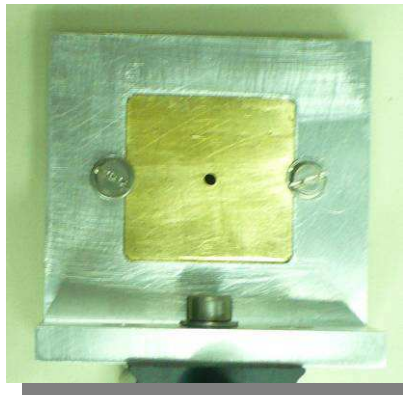


Experimental setup equipment

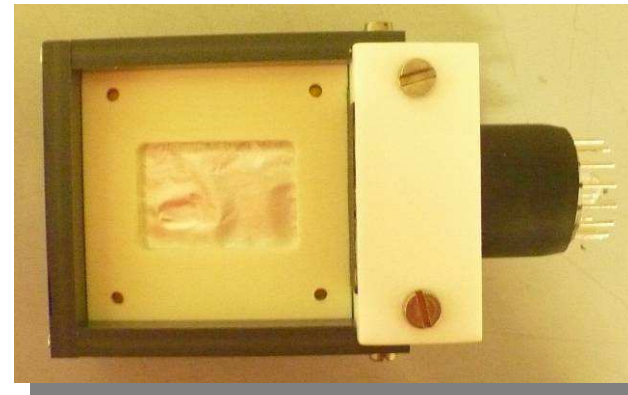
Aluminum degrader



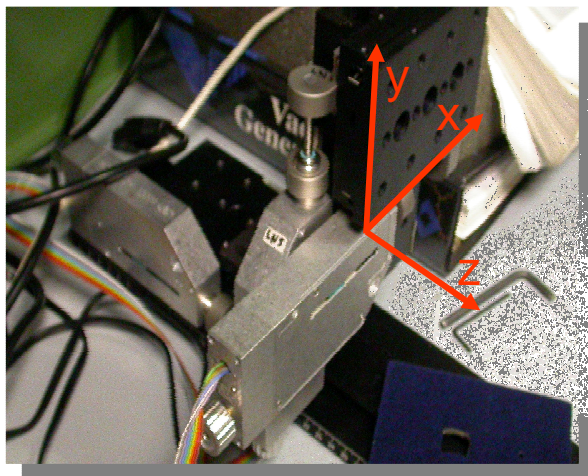
Beam collimator



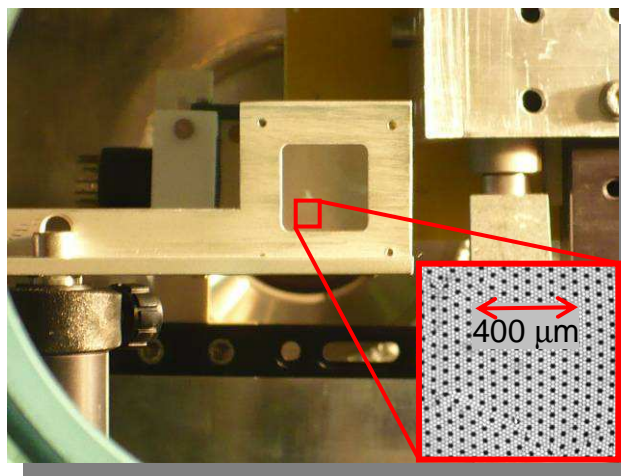
Scintillator thin ($200\ \mu\text{m}$) plate with PMT



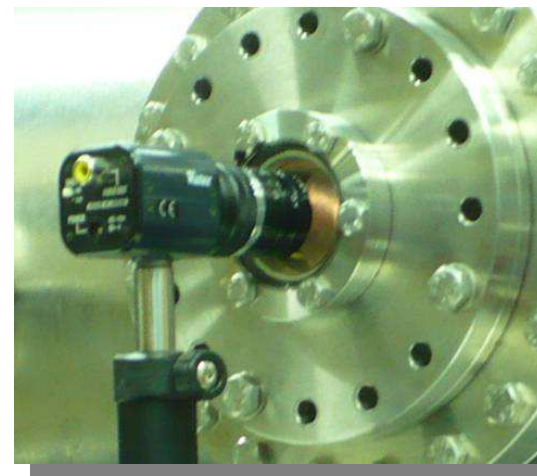
Linear translation stages



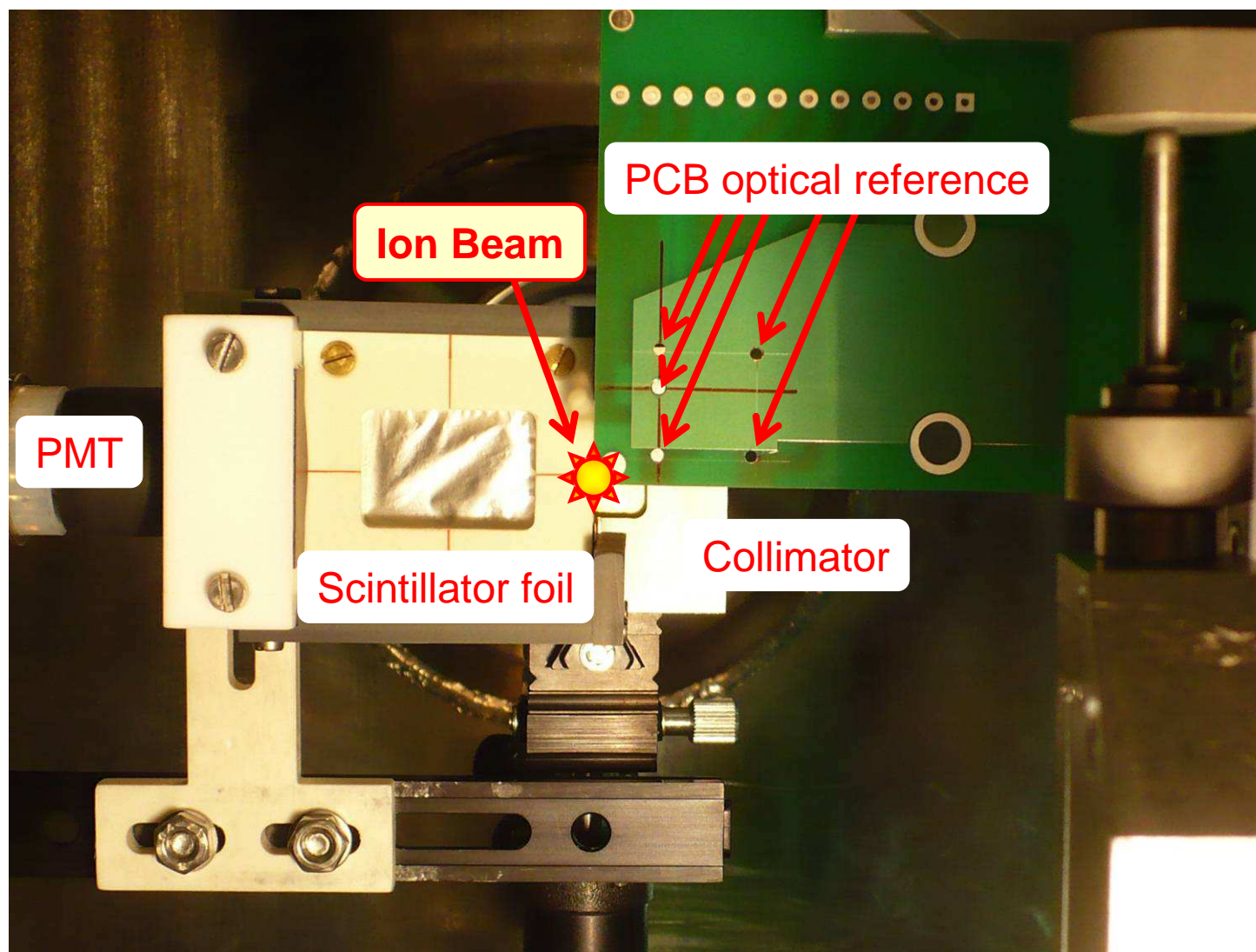
SFOP
(Scintillating Fiber Optic Plate)



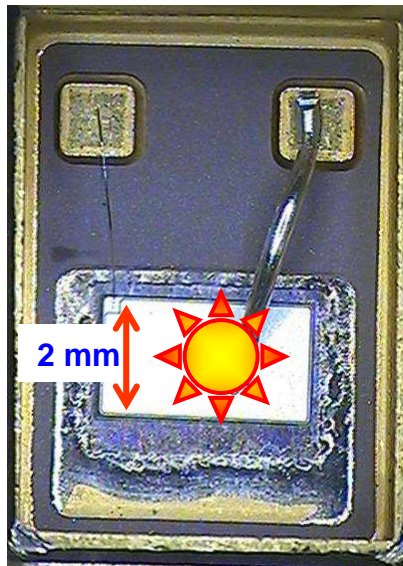
High sensitivity
CCD Camera



Back view



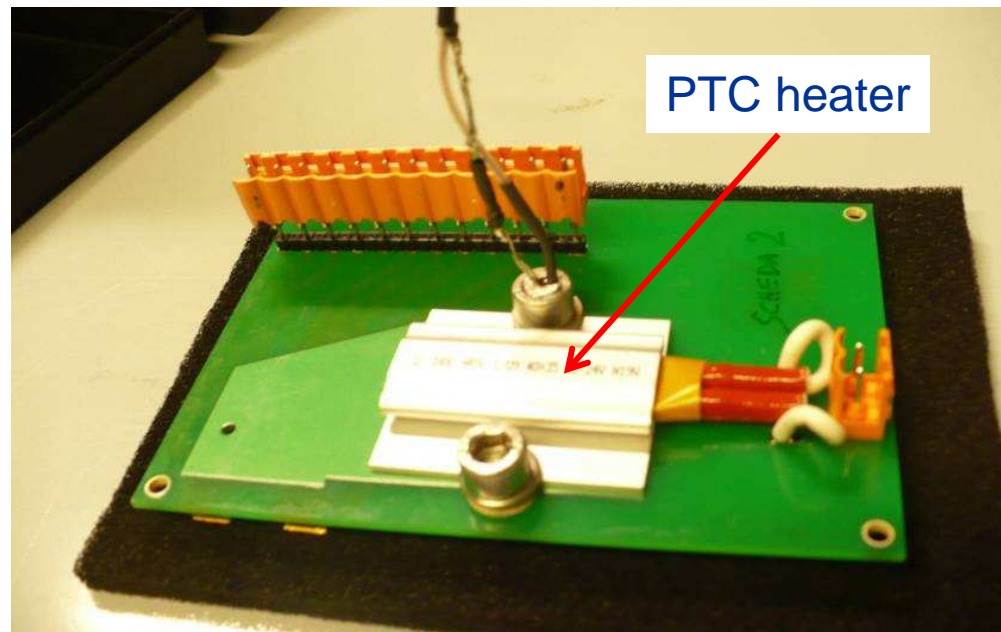
Device Under Test
"Power MOSFET"



*Two different tests performed on **DUTs**:*

- **SEB (Single Event Burnout)**
- **SEGR (Single Event Gate Rupture)**

A PTC heater was assembled on the back side of the irradiation board, near the DUTs and powered when necessary to perform the test at high-temperature (80 °C).

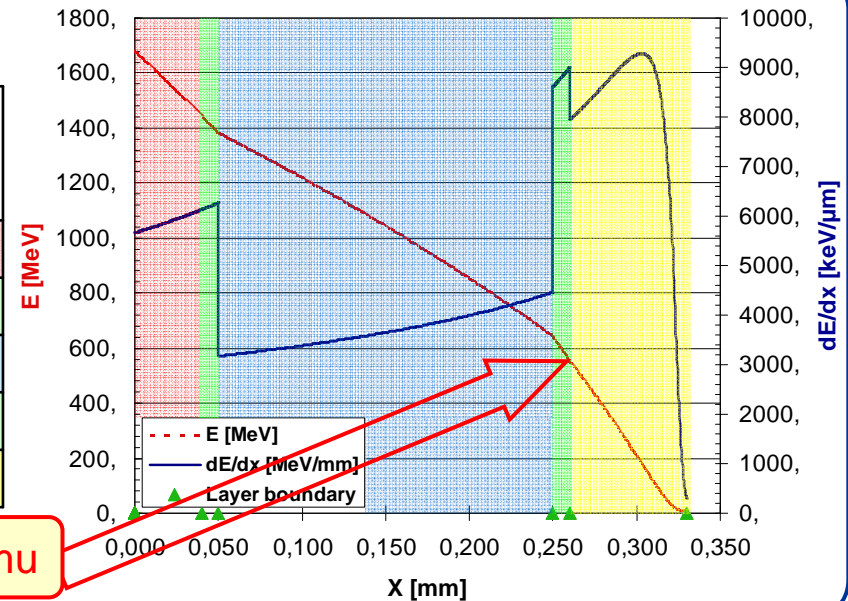


SRIM Simulation: Energy loss

	Material	Thickness [μm]	Input Energy [MeV]	Energy loss [MeV]
Degrader	Al	40	1680.00	235.46
Reflector	Al	10	1444.54	62.00
Scintillator	Pilot U	200	1382.54	740.51
Reflector	Al	10	642.03	88.03
Target	Si		554.00	554.00

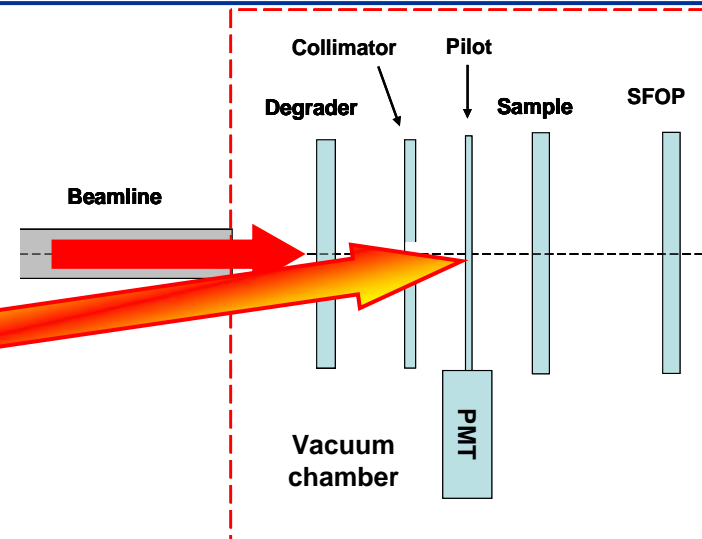
^{84}Kr @ 20 MeV/amu

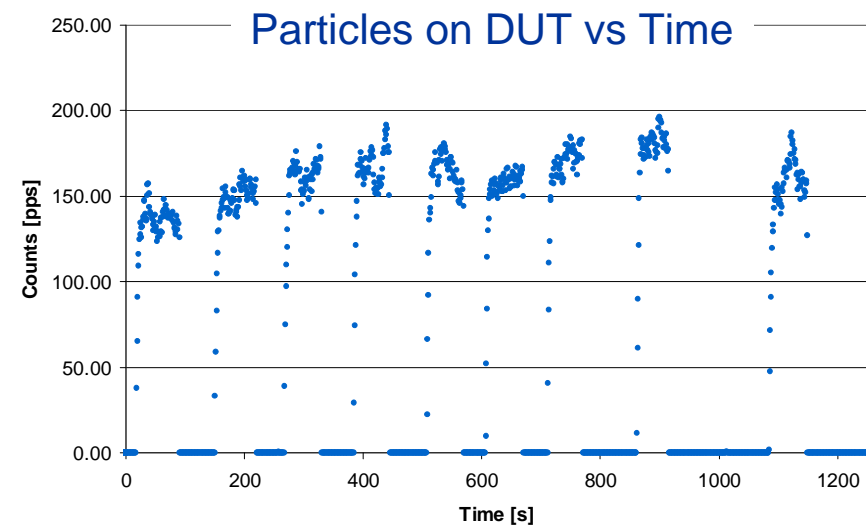
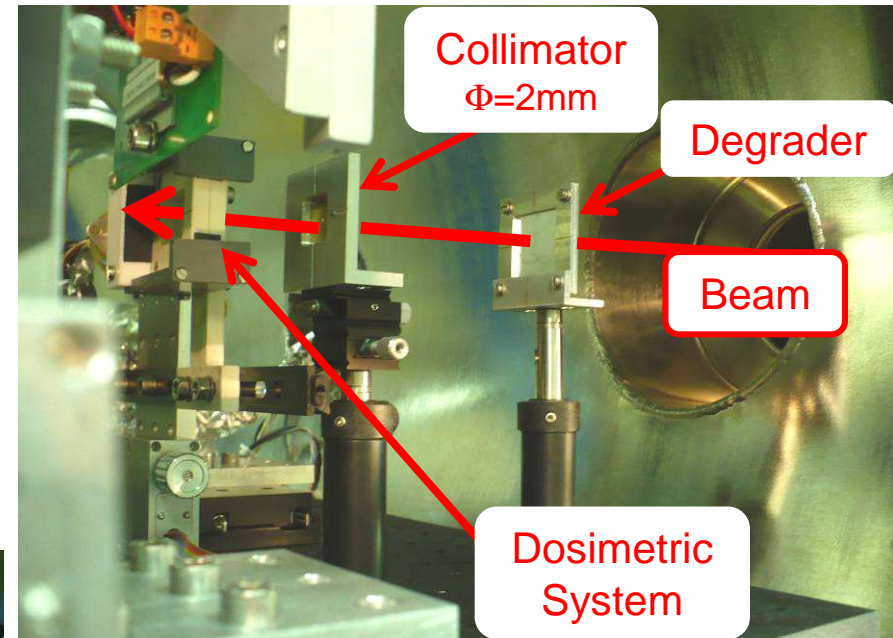
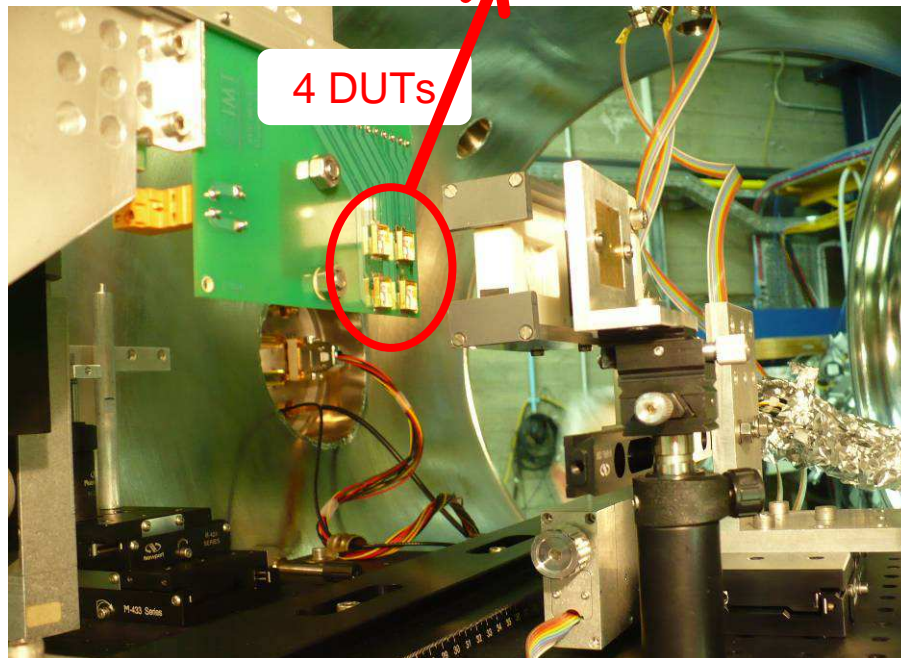
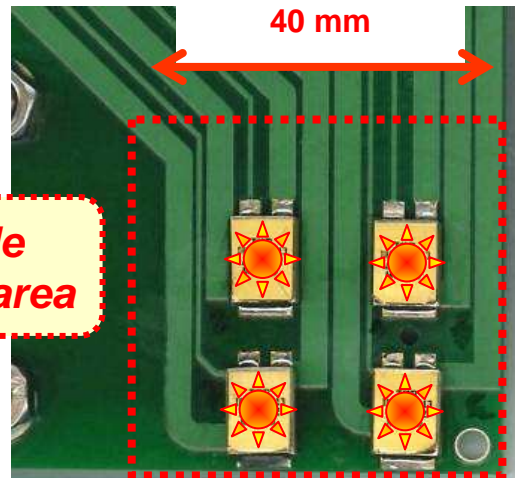
^{84}Kr @ 6.6 MeV/amu

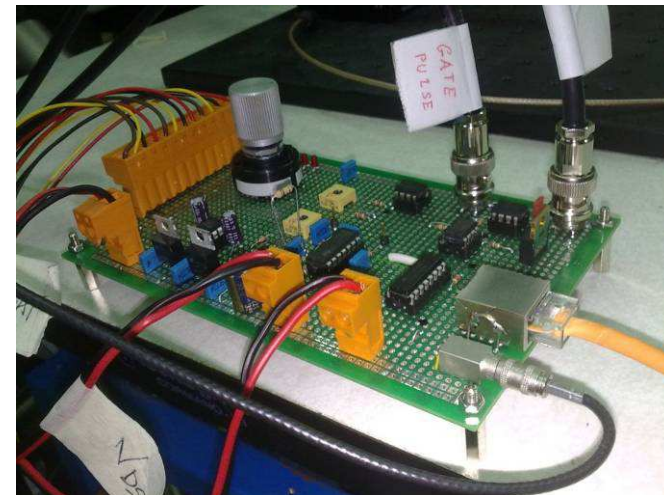
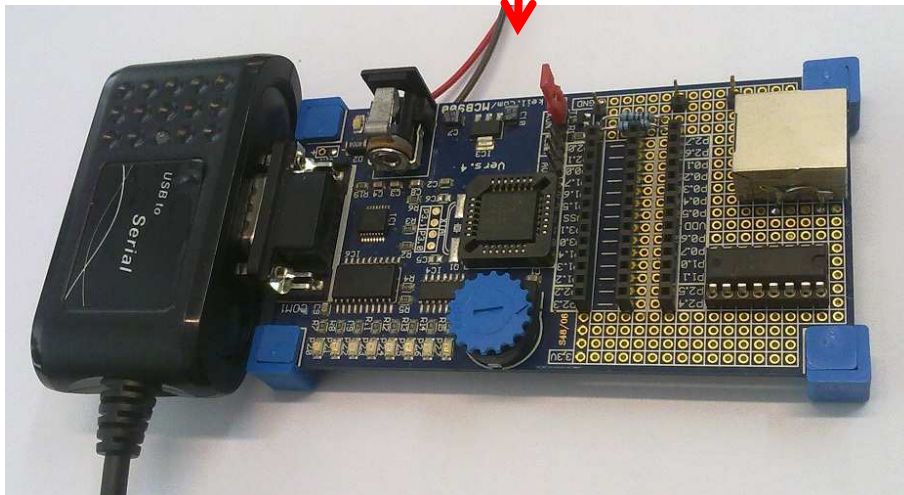
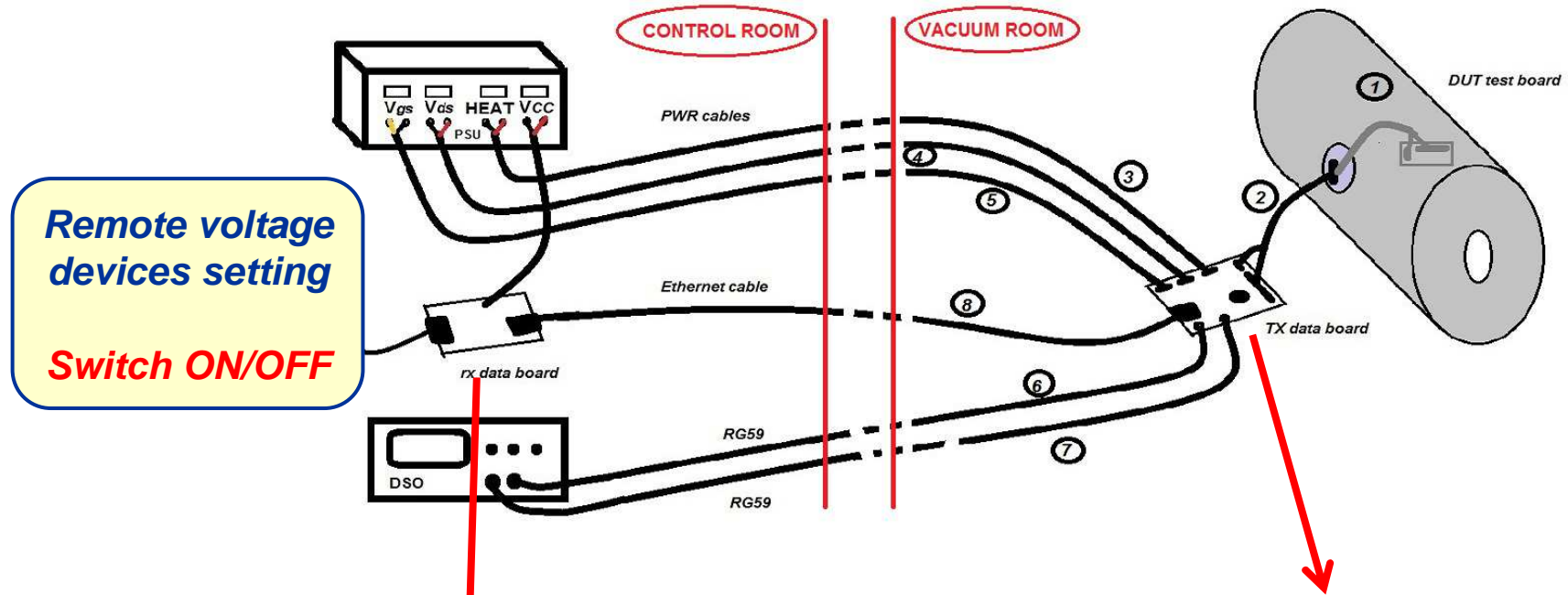


SRIM Simulation: LET at different Degrader thickness

Al thickness [μm]	PMT present	Input Energy [MeV]	Range in Silicon [μm]
0	Yes	891.20	111
40	Yes	554.00	67
80	Yes	142.48	22
40	No	1444.54	210





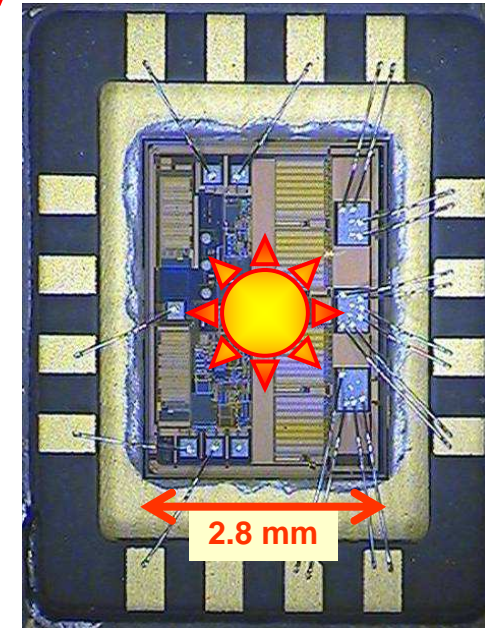


SEE measured at INFN-LNS March 2013 test

Same experimental setup used during first campaign except:

- Collimator diameter
- Degradar thickness
- Ion species

SET (Single Event Transient) characterization was performed on adjustable positive voltage regulator at different load conditions.



Still ongoing analysis

Ion	Energy (MeV)	LET (MeV mg ⁻¹ cm ²)	Range in Si (μm)
⁴⁰ Ar	507	8	180
⁸⁴ Kr	747	30	93
¹²⁹ Xe	612	60	50



Summary

- Able to work In-vacuum
- Micro-positioning system
- **SEE tests successful performed**
- Ability to fulfill customer specifications

Thank you for your attention

